

6

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D

D

C

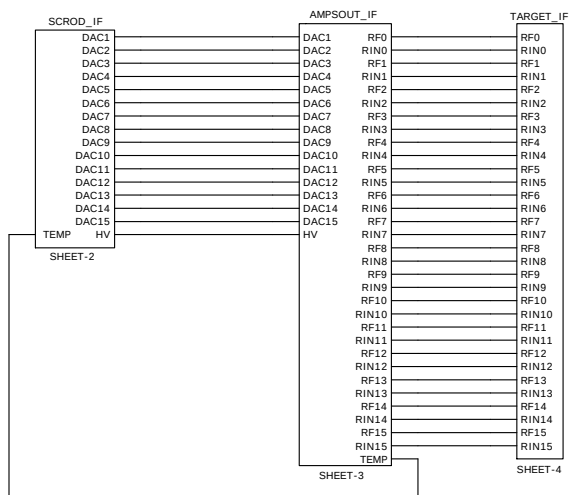
C

B

B

A

A



Layer Definitions

Top Copper routing

Layer 2 split AGND/GND

Layer 3 split A.5V

Bottom Copper split Vped/D2.5V fill

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TITLE: eKLM DACmon Daughtercard

IDL_10_039



Design:

GSV

Page Description:

TOP Block
DC_DACmon_RevA

REV:

A

DATED: 31-DEC-2010

[TOP]

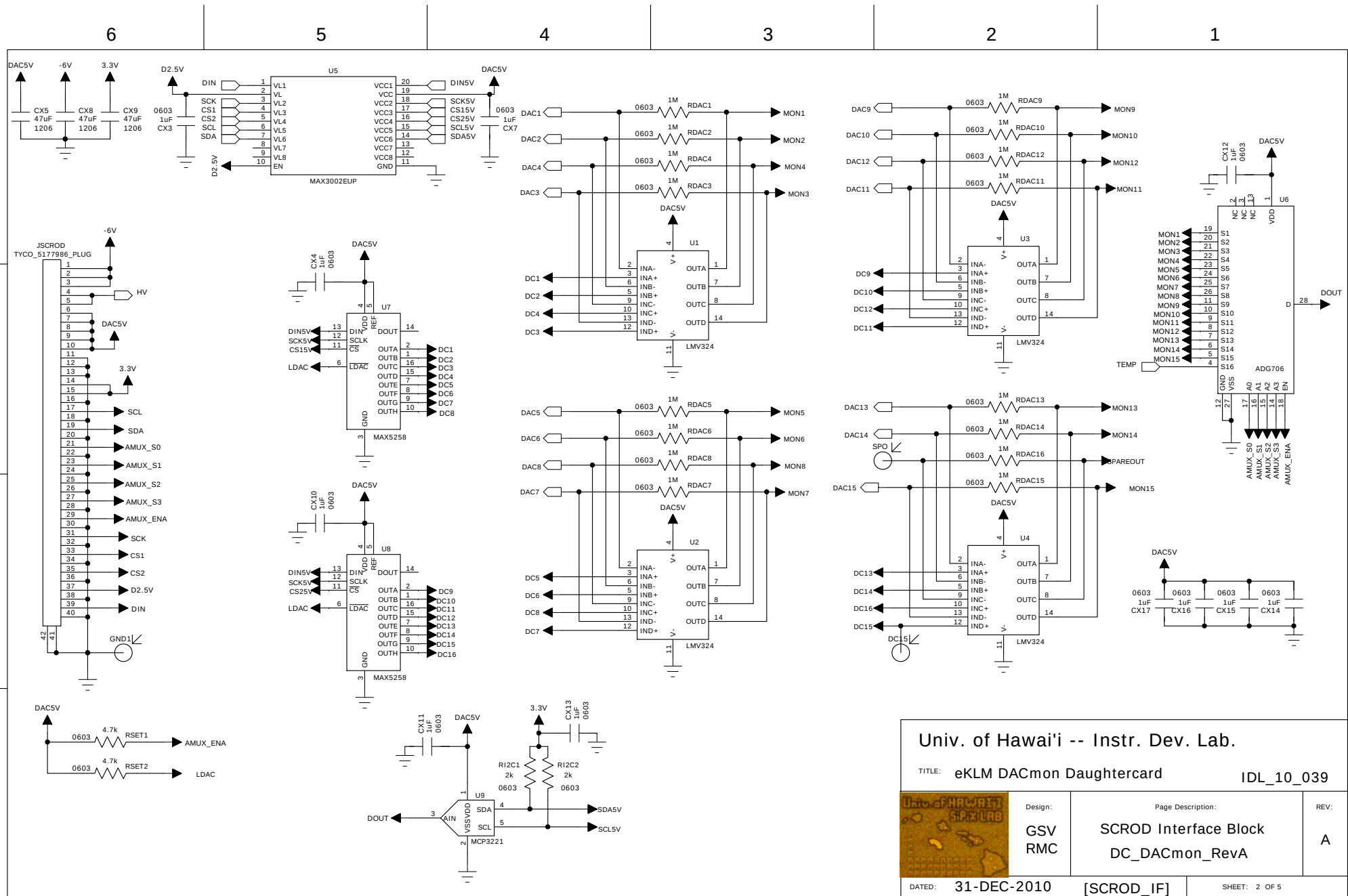
SHEET: 1 OF 5

D

C

B

A



D

C

B

A

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TITLE: eKLM DACmon Daughtercard

IDL_10_039



Design:
GSV
RMC

Page Description:
SCROD Interface Block
DC_DACmon_RevA

REV:
A

DATED: 31-DEC-2010

[SCROD_IF]

SHEET: 2 OF 5

D

C

B

A

D

C

B

A

6

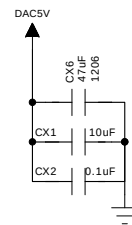
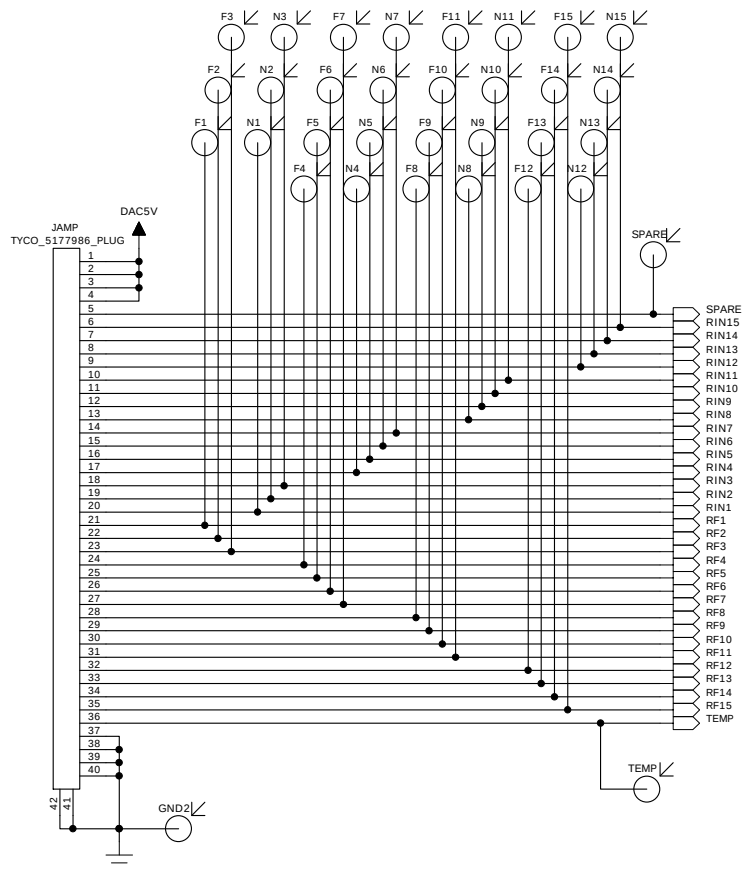
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TITLE: eKLM DACmon Daughtercard

IDL_10_039

Design:
GSVPage Description:
Amp Carrier Interface
DC_DACmon_RevAREV:
A

DATED: 30-DEC-2010

[AMPSOUT_IF]

SHEET: 3 OF 5

6

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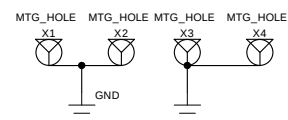
C

B

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TITLE: eKLM DACmon Daughtercard

IDL_10_039



Design:

GSV

Page Description:

Misc Power Items
DC_DACmon_RevA

REV:

A

DATED: 30-DEC-2010

[POWER]

SHEET: 5 OF 5